

#### SPECIFICATIONS





Part Number	Chip Material	Color of Emission	Lens Type	Description	
CDQA39RR2WF	InGaAIP	Red	White Segment	Common Anode	





## ABSOLUTE MAXIMUM RATINGS

#### (TA=25°C)

Parameter	Symbol	Max Rating	Unit				
Power Dissipation	PD	70	mW				
Pulse Forward Current	lfp	90	mA				
Continuous Forward Current	lF	25	mA				
Reverse Voltage Segment	VR	5	V				
Operating Temperature Range	Topr	-25~+85	°C				
Storage Temperature Range	Тѕтс	-25~+85	°C				
IFP = Pulse Width $\leq$ 10 ms, Duty Ratio $\leq$ 1/10. Soldering Condition: 260 °C/ 5sec							

# OPTICAL-ELECTRICAL CHARACTERISTICS

# (TA=25°C)

Deremeter	Symbol	Test Condition	Value			Linit
		Test Condition	Min	Тур	Max	Unit
Luminous Intensity	١v	l⊧ = 20mA	-	55	-	mcd
Forward Voltage	Vf	l⊧ = 20mA	-	2.0	2.6	V
Reverse Leakage Current	lR	V <sub>R</sub> = 5V	-	-	10	μA
Peak Wavelength	λP	l⊧ = 20mA	-	650	-	nm
Dominant Wavelength	λD	l⊧ = 20mA	-	639	-	nm
Spectral Radiation Bandwidth	Δλ	l⊧ = 20mA	-	20	-	nm





#### TYPICAL INTERNAL EQUIVALENT CIRCUIT







# **OPTICAL CHARACTERISTIC CURVES**



11111 100 1000

FORWARD CURRENT (mA) Fig.2 RELATIVE INTENSITY VS. FORWARD CURRENT



Fig.4 RELATIVE INTENSITY VS. TEMPERATURE



Fig.6 MAX. ALLOWABLE DC CURRENT VS. AMBIENT TEMPERATURE





#### SOLDERING CONDITIONS – DISPLAY TYPE LED

# RECOMMEND SOLDERING PROFILE



## SOLDERING IRON

Basic spec is  $\leq$ 4 sec when 260°C. If temperature is higher, time should be shorter (+10°C→1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.

## REWORK

Customer must finish rework within ≦4 sec under 245°C.

